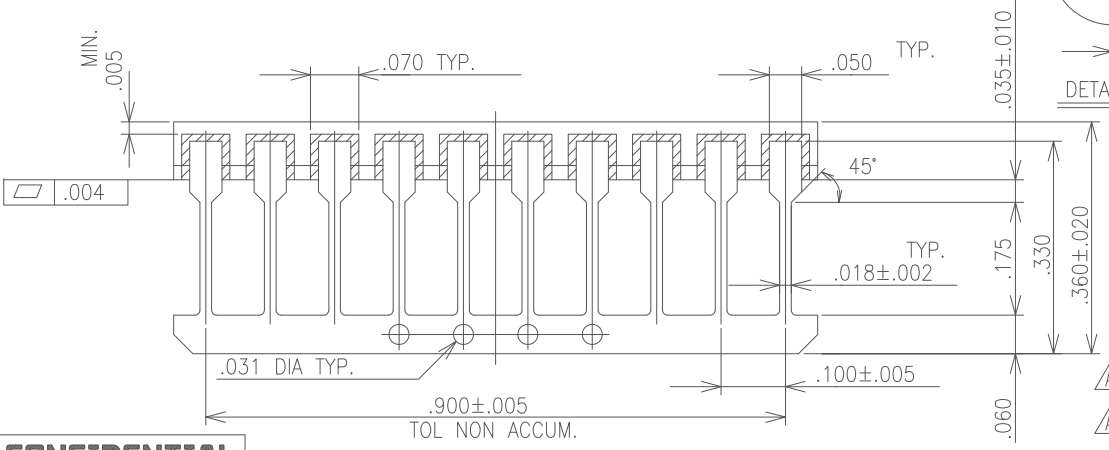


OPTION TABLE

PART No.	NOTCH AREA METALLIZED	OTHER
1	WITH METALLIZATION	—
2	WITHOUT METALLIZATION	—
3	WITHOUT METALLIZATION	ESD TRAY



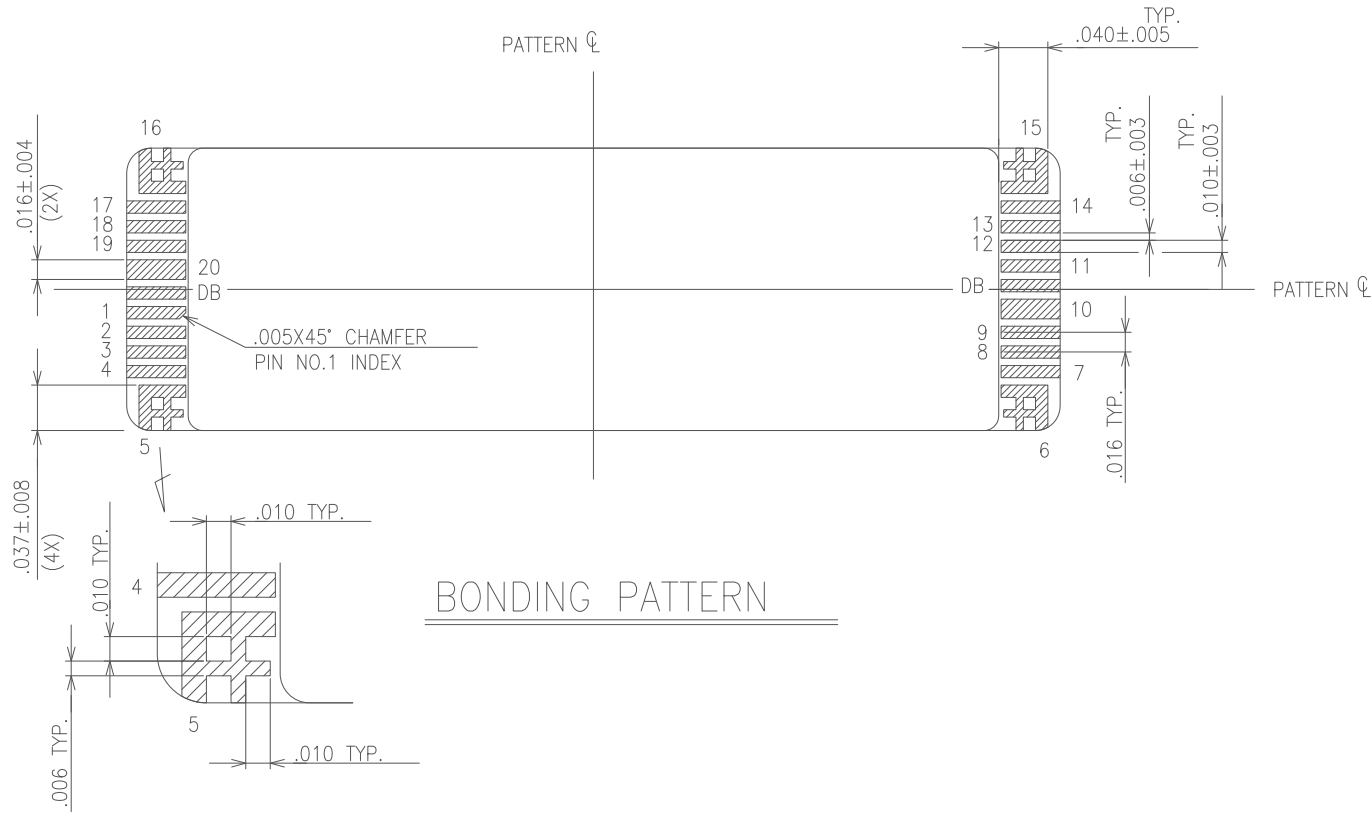
- NOTES :
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY LEADS.
 5. DB PADS SHALL BE ELECTRICALLY CONNECTED TO THE DIE ATTACH PAD.
 6. LEAD RESISTANCE : 0.5 OHM MAX.
 7. WIRE BOND PAD CONNECTED TO CORRESPONDED OUTER LEAD.
 8. MISALIGNMENT OF METALLIZATION PATTERN IN CAVITY SHALL BE ACCEPTED DUE TO LAYER MISALIGNMENT.

SB020AA277-3	S=0 D=0
SB020AA277-2	S=0 D=0
SB020AA277-1	S=0 D=0

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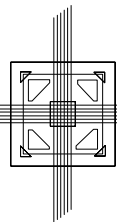
MODIFICATION	DESCRIPTION	DATE	DRAWN	CHECKED	APPROVED	NAME	SCALE	MATERIAL	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
ⓑ	ADDED: PART No.3. DELETED: VENDOR'S OPTION.	MAR.18.'15	Y.O/M.S	K.Y	H.B	20 LEAD SIDE BRAZED PACKAGE	5/1	AS INDICATED	±.005	S.F	S.T	K.M	APR.4.'92
Ⓐ	ADDED: PART No.2 AND NOTE 7,8 CHANGED	OCT.03.'07	S.N	TO.H/M.SU	H.SA	KYOCERA		KYOCERA CORPORATION KYOTO JAPAN		Y.O/M.S			
										DRAWING NO.		SHEET	
										KD-S92277-B		1/2	





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MODIFICATION						NAME 20 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN S.F	CHECKED S.T	APPROVED K.M	DATE APR.4.'92
						SCALE 10 / 1	MATERIAL	Y.O/M.S			
							THIRD ANGLE PROJECTION				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	KYOCERA	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-S92277-B		SHEET 2/2	



SPECTRUM
SEMICONDUCTOR MATERIALS, INC.

